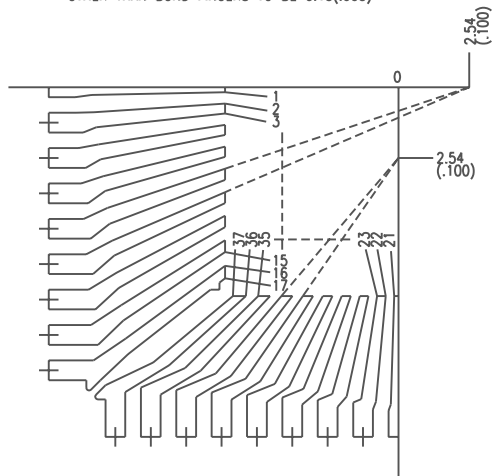
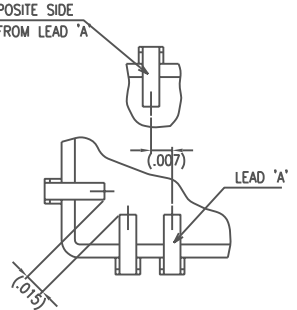
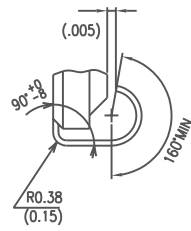
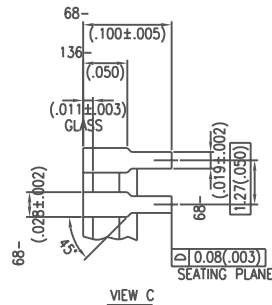
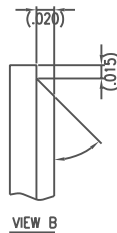
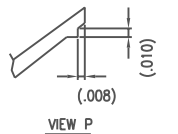
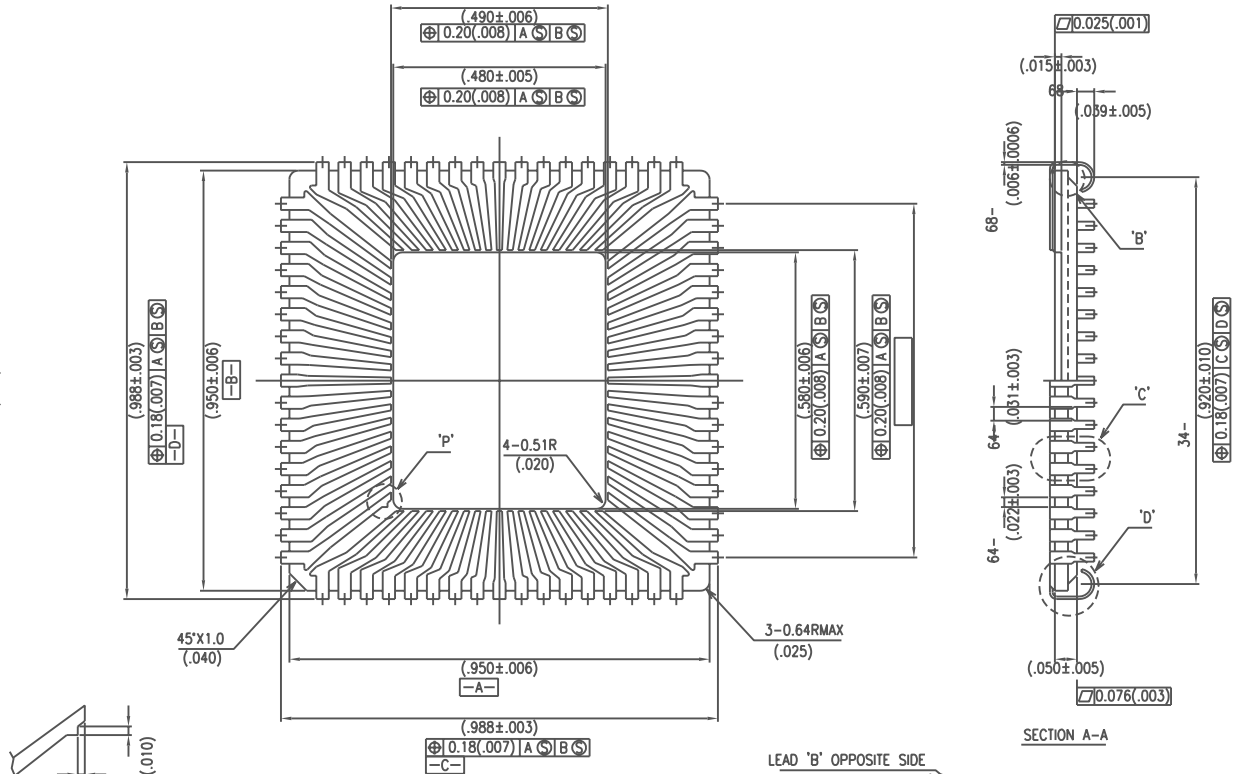


NOTES

1. MATERIALS
 CERAMIC TO OPAQUE, 90-94% Al₂O₃
 SOLDER GLASS TO BE 7583.
 MAX PULLBACK TO BE 0.25(.010)
 FROM CERAMIC EDGE.
 DIE ATTACH AREA TO BE Au 120
 MICROINCH MIN.
 LEAD FRAME TO BE ALLOY 42 OR
 TYPE B MIL 38510 PARAGRAPH
 3.5.6.1. WITH ALUMINIUM
 BOND PADS 100 MICROINCH THICK
 AND 35MILS IN LENGTH WITH NO PULL BACK.
2. THERE WILL BE NO UNSUPPORTED
 BOND PADS GREATER THAN 0.25(.010)
3. ADJACENT BOND PADS MUST BE
 CO-PLANER WITHIN 0.15(.006)
 TOTAL CO-PLANARITY NO GREATER
 THAN 0.25(.010).
4. THERE WILL BE NO NICKS, CUTS
 OR GLASS IN THE BOND RADIUS
5. MINIMUM INTERNAL METAL SEPARATION
 OTHER THAN BOND FINGERS TO BE 0.13(.005)



No.	ANGLE	No.	ANGLE
1	1.16 °	21	1.76 °
2	3.82 °	22	5.28 °
3	6.13 °	23	8.78 °
4	8.77 °	24	12.25 °
5	11.06 °	25	15.67 °
6	13.66 °	26	19.04 °
7	15.90 °	27	22.36 °
8	18.44 °	28	25.56 °
9	20.79 °	29	28.70 °
10	23.25 °	30	31.75 °
11	25.37 °	31	34.70 °
12	27.75 °	32	37.54 °
13	29.79 °	33	40.29 °
14	32.07 °	34	42.92 °
15	34.01 °	35	45.45 °
16	36.19 °	36	47.87 °
17	38.04 °	37	50.18 °



MODIFICATIONS	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 68LD QUAD CERPAC'J'(480X580)		TOLERANCES: UNLESS OTHERWISE SPECIFIED		DRAWN K. OKADA		CHECKED N. GODA	
SCALE 5 : 1		MATERIAL		APPROVED J. TAMAMURA		DATE AUG.27'90	
KYOCERA CORPORATION				KYOTO JAPAN		DWG No. QC-068286-J	

